Lattice Semiconductor Corporation - LCMXO640E-4TN144I Datasheet

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Active
Number of LABs/CLBs	80
Number of Logic Elements/Cells	640
Total RAM Bits	-
Number of I/O	113
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	144-LQFP
Supplier Device Package	144-TQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lcmxo640e-4tn144i

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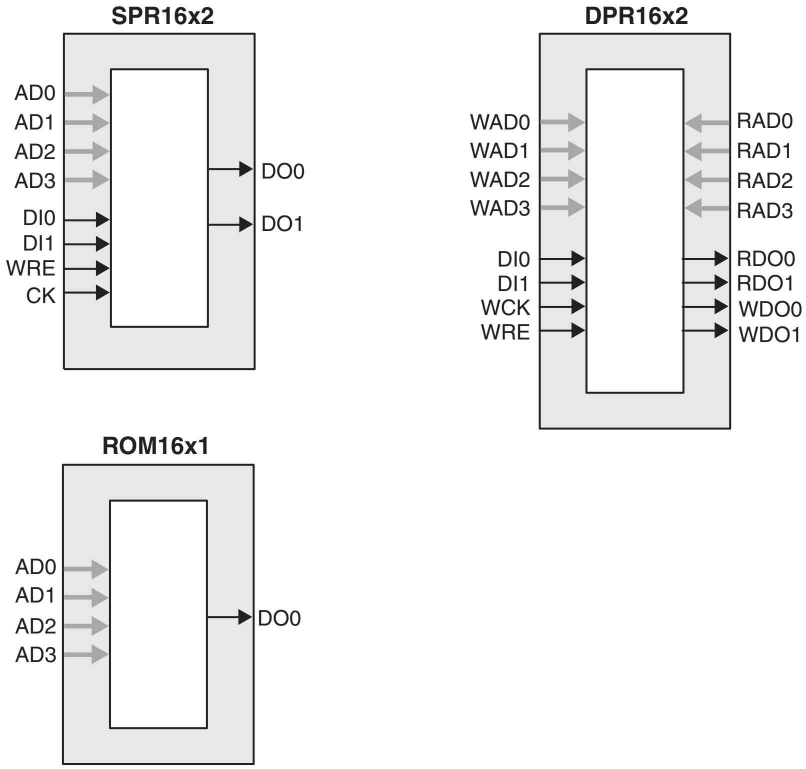
Figure 2-6. Distributed Memory Primitives



ROM Mode: The ROM mode uses the same principal as the RAM modes, but without the Write port. Pre-loading is accomplished through the programming interface during configuration.

PFU Modes of Operation

Slices can be combined within a PFU to form larger functions. Table 2-4 tabulates these modes and documents the functionality possible at the PFU level.

Table 2-4. PFU Modes of Operation

Logic	Ripple	RAM	ROM
LUT 4x8 or MUX 2x1 x 8	2-bit Add x 4	SPR16x2 x 4 DPR16x2 x 2	ROM16x1 x 8
LUT 5x4 or MUX 4x1 x 4	2-bit Sub x 4	SPR16x4 x 2 DPR16x4 x 1	ROM16x2 x 4
LUT 6x 2 or MUX 8x1 x 2	2-bit Counter x 4	SPR16x8 x 1	ROM16x4 x 2
LUT 7x1 or MUX 16x1 x 1	2-bit Comp x 4		ROM16x8 x 1

Routing

There are many resources provided in the MachXO devices to route signals individually or as buses with related control signals. The routing resources consist of switching circuitry, buffers and metal interconnect (routing) segments.

The inter-PFU connections are made with three different types of routing resources: x1 (spans two PFUs), x2 (spans three PFUs) and x6 (spans seven PFUs). The x1, x2, and x6 connections provide fast and efficient connections in the horizontal and vertical directions.

The EBR memory supports three forms of write behavior for single or dual port operation:

1. **Normal** – data on the output appears only during the read cycle. During a write cycle, the data (at the current address) does not appear on the output. This mode is supported for all data widths.

2. **Write Through** – a copy of the input data appears at the output of the same port. This mode is supported for all data widths.

3. **Read-Before-Write** – when new data is being written, the old contents of the address appears at the output. This mode is supported for x9, x18 and x36 data widths.

FIFO Configuration

The FIFO has a write port with Data-in, CEW, WE and CLKW signals. There is a separate read port with Data-out, RCE, RE and CLKR signals. The FIFO internally generates Almost Full, Full, Almost Empty and Empty Flags. The Full and Almost Full flags are registered with CLKW. The Empty and Almost Empty flags are registered with CLKR. The range of programming values for these flags are in Table 2-7.

Table 2-7. Programmable FIFO Flag Ranges

Flag Name	Programming Range
Full (FF)	1 to (up to 2^N-1)
Almost Full (AF)	1 to Full-1
Almost Empty (AE)	1 to Full-1
Empty (EF)	0

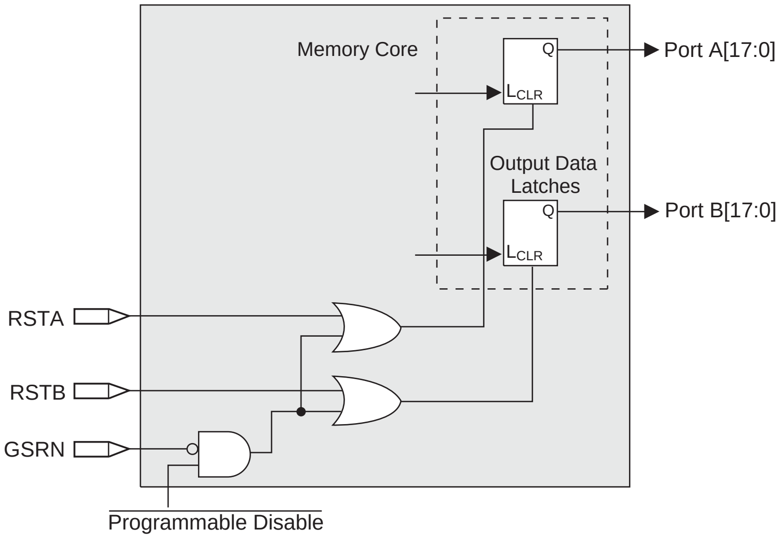
N = Address bit width

The FIFO state machine supports two types of reset signals: RSTA and RSTB. The RSTA signal is a global reset that clears the contents of the FIFO by resetting the read/write pointer and puts the FIFO flags in their initial reset state. The RSTB signal is used to reset the read pointer. The purpose of this reset is to retransmit the data that is in the FIFO. In these applications it is important to keep careful track of when a packet is written into or read from the FIFO.

Memory Core Reset

The memory array in the EBR utilizes latches at the A and B output ports. These latches can be reset asynchronously. RSTA and RSTB are local signals, which reset the output latches associated with Port A and Port B respectively. The Global Reset (GSRN) signal resets both ports. The output data latches and associated resets for both ports are as shown in Figure 2-13.

Figure 2-13. Memory Core Reset

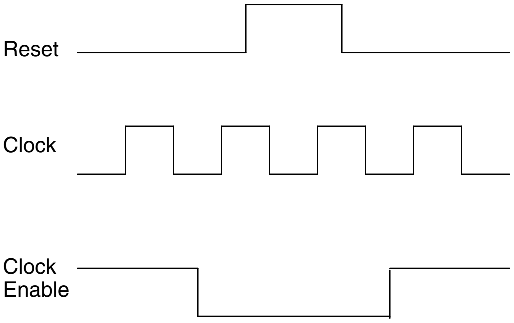


For further information on the sysMEM EBR block, see the details of additional technical documentation at the end of this data sheet.

EBR Asynchronous Reset

EBR asynchronous reset or GSR (if used) can only be applied if all clock enables are low for a clock cycle before the reset is applied and released a clock cycle after the reset is released, as shown in Figure 2-14. The GSR input to the EBR is always asynchronous.

Figure 2-14. EBR Asynchronous Reset (Including GSR) Timing Diagram



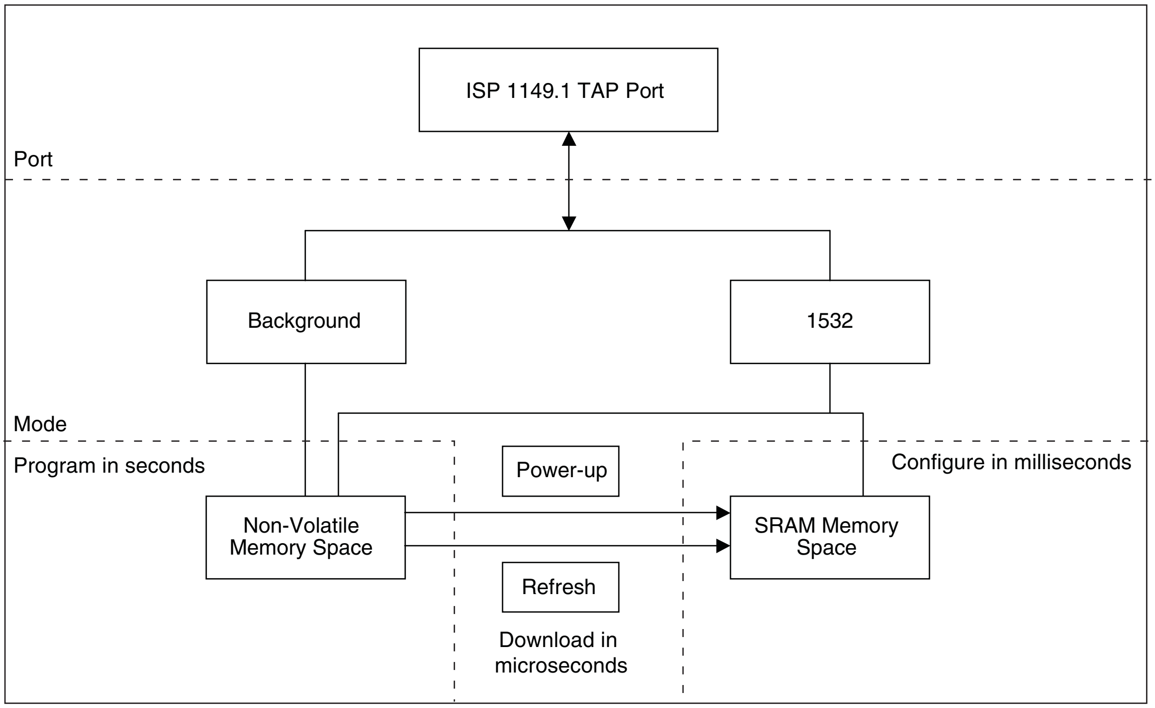
If all clock enables remain enabled, the EBR asynchronous reset or GSR may only be applied and released after the EBR read and write clock inputs are in a steady state condition for a minimum of $1/f_{MAX}$ (EBR clock). The reset release must adhere to the EBR synchronous reset setup time before the next active read or write clock edge.

If an EBR is pre-loaded during configuration, the GSR input must be disabled or the release of the GSR during device Wake Up must occur before the release of the device I/Os becoming active.

These instructions apply to all EBR RAM, ROM and FIFO implementations. For the EBR FIFO mode, the GSR signal is always enabled and the WE and RE signals act like the clock enable signals in Figure 2-14. The reset timing rules apply to the RPReset input vs the RE input and the RST input vs. the WE and RE inputs. Both RST and RPReset are always asynchronous EBR inputs.

Note that there are no reset restrictions if the EBR synchronous reset is used and the EBR GSR input is disabled

Figure 2-22. MachXO Configuration and Programming



Density Shifting

The MachXO family has been designed to enable density migration in the same package. Furthermore, the architecture ensures a high success rate when performing design migration from lower density parts to higher density parts. In many cases, it is also possible to shift a lower utilization design targeted for a high-density device to a lower density device. However, the exact details of the final resource utilization will impact the likely success in each case.

Supply Current (Sleep Mode)[1, 2]

Symbol	Parameter	Device	Typ.[3]	Max.	Units
I_{CC}	Core Power Supply	LCMXO256C	12	25	µA
		LCMXO640C	12	25	µA
		LCMXO1200C	12	25	µA
		LCMXO2280C	12	25	µA
I_{CCAUX}	Auxiliary Power Supply	LCMXO256C	1	15	µA
		LCMXO640C	1	25	µA
		LCMXO1200C	1	45	µA
		LCMXO2280C	1	85	µA
I_{CCIO}	Bank Power Supply[4]	All LCMXO ‘C’ Devices	2	30	µA

1. Assumes all inputs are configured as LVCMOS and held at the VCCIO or GND.
2. Frequency = 0MHz.
3. T_A = 25°C, power supplies at nominal voltage.
4. Per Bank.

Supply Current (Standby)[1, 2, 3, 4]

Over Recommended Operating Conditions

Symbol	Parameter	Device	Typ.[5]	Units
I_{CC}	Core Power Supply	LCMXO256C	7	mA
		LCMXO640C	9	mA
		LCMXO1200C	14	mA
		LCMXO2280C	20	mA
		LCMXO256E	4	mA
		LCMXO640E	6	mA
		LCMXO1200E	10	mA
		LCMXO2280E	12	mA
I_{CCAUX}	Auxiliary Power Supply V_{CCAUX} = 3.3V	LCMXO256E/C	5	mA
		LCMXO640E/C	7	mA
		LCMXO1200E/C	12	mA
		LCMXO2280E/C	13	mA
I_{CCIO}	Bank Power Supply[6]	All devices	2	mA

1. For further information on supply current, please see details of additional technical documentation at the end of this data sheet.
2. Assumes all outputs are tristated, all inputs are configured as LVCMOS and held at V_{CCIO} or GND.
3. Frequency = 0MHz.
4. User pattern = blank.
5. T_J = 25°C, power supplies at nominal voltage.
6. Per Bank. V_{CCIO} = 2.5V. Does not include pull-up/pull-down.

Table 3-1. LVDS DC Conditions

Over Recommended Operating Conditions

Parameter	Description	Typical	Units
Z_{OUT}	Output impedance	20	Ω
R_S	Driver series resistor	294	Ω
R_P	Driver parallel resistor	121	Ω
R_T	Receiver termination	100	Ω
V_{OH}	Output high voltage	1.43	V
V_{OL}	Output low voltage	1.07	V
V_{OD}	Output differential voltage	0.35	V
V_{CM}	Output common mode voltage	1.25	V
Z_{BACK}	Back impedance	100	Ω
I_{DC}	DC output current	3.66	mA

BLVDS

The MachXO family supports the BLVDS standard through emulation. The output is emulated using complementary LVCMOS outputs in conjunction with a parallel external resistor across the driver outputs. The input standard is supported by the LVDS differential input buffer on certain devices. BLVDS is intended for use when multi-drop and bi-directional multi-point differential signaling is required. The scheme shown in Figure 3-2 is one possible solution for bi-directional multi-point differential signals.

Figure 3-2. BLVDS Multi-point Output Example

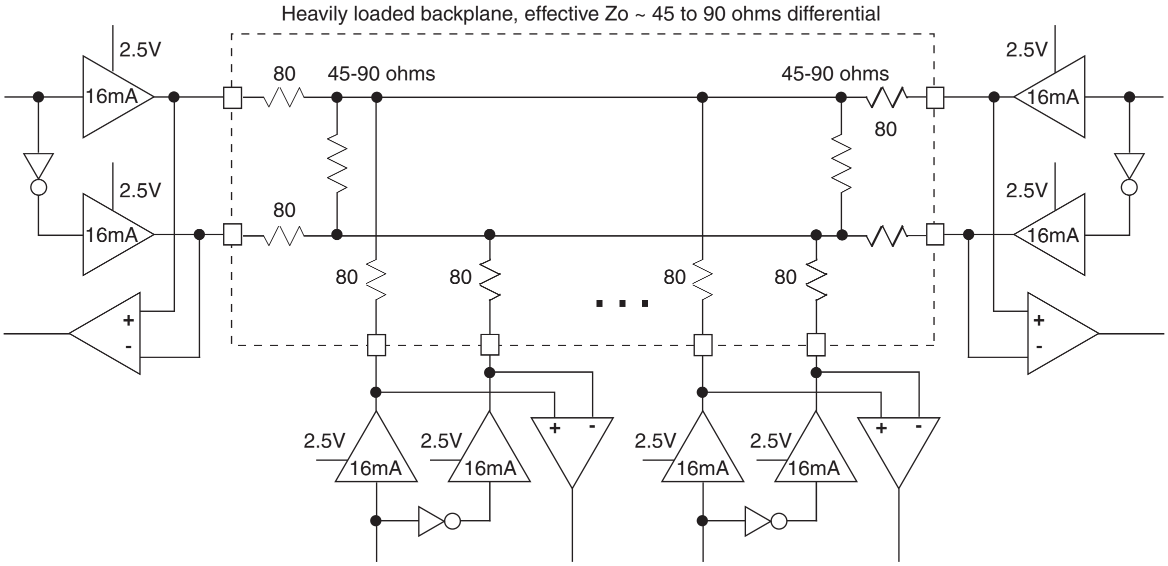


Table 3-2. BLVDS DC Conditions[1]

Over Recommended Operating Conditions

Symbol	Description	Nominal		Units
		Zo = 45	Zo = 90	
Z_{OUT}	Output impedance	100	100	Ohms
R_{TLEFT}	Left end termination	45	90	Ohms
R_{TRIGHT}	Right end termination	45	90	Ohms
V_{OH}	Output high voltage	1.375	1.48	V
V_{OL}	Output low voltage	1.125	1.02	V
V_{OD}	Output differential voltage	0.25	0.46	V
V_{CM}	Output common mode voltage	1.25	1.25	V
I_{DC}	DC output current	11.2	10.2	mA

1. For input buffer, see LVDS table.

LVPECL

The MachXO family supports the differential LVPECL standard through emulation. This output standard is emulated using complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs on all the devices. The LVPECL input standard is supported by the LVDS differential input buffer on certain devices. The scheme shown in Figure 3-3 is one possible solution for point-to-point signals.

Figure 3-3. Differential LVPECL

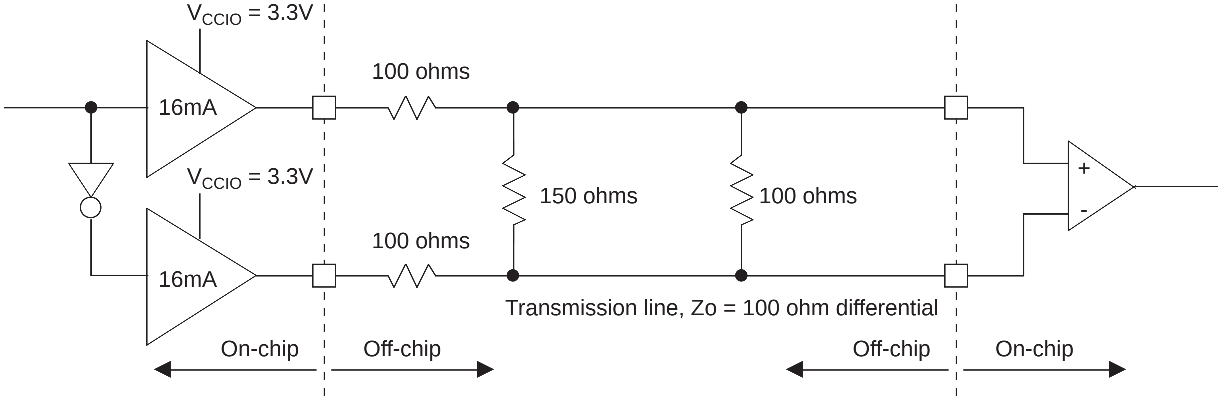


Table 3-3. LVPECL DC Conditions[1]

Over Recommended Operating Conditions

Symbol	Description	Nominal	Units
Z_{OUT}	Output impedance	100	Ohms
R_P	Driver parallel resistor	150	Ohms
R_T	Receiver termination	100	Ohms
V_{OH}	Output high voltage	2.03	V
V_{OL}	Output low voltage	1.27	V
V_{OD}	Output differential voltage	0.76	V
V_{CM}	Output common mode voltage	1.65	V
Z_{BACK}	Back impedance	85.7	Ohms
I_{DC}	DC output current	12.7	mA

1. For input buffer, see LVDS table.

For further information on LVPECL, BLVDS and other differential interfaces please see details of additional technical documentation at the end of the data sheet.

RSDS

The MachXO family supports the differential RSDS standard. The output standard is emulated using complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs on all the devices. The RSDS input standard is supported by the LVDS differential input buffer on certain devices. The scheme shown in Figure 3-4 is one possible solution for RSDS standard implementation. Use LVDS25E mode with suggested resistors for RSDS operation. Resistor values in Figure 3-4 are industry standard values for 1% resistors.

Figure 3-4. RSDS (Reduced Swing Differential Standard)

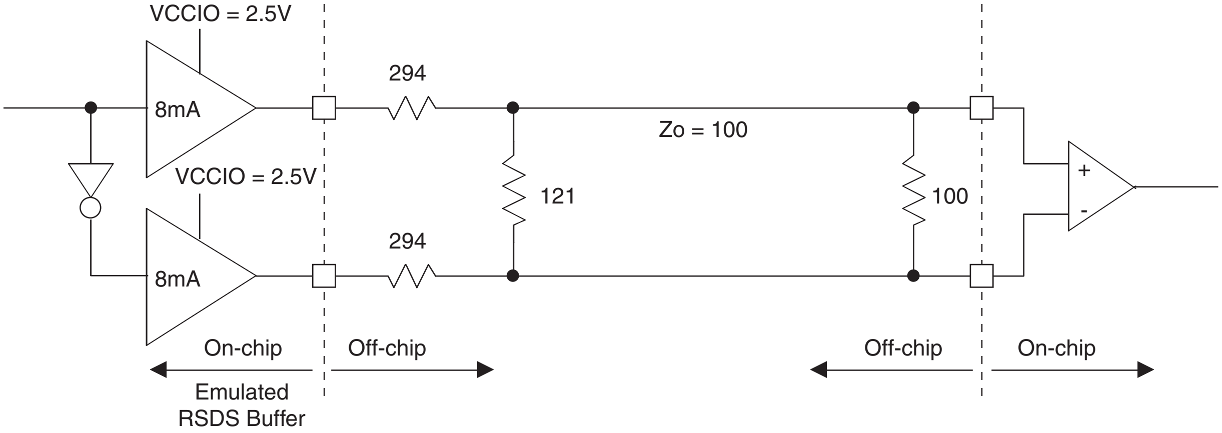


Table 3-4. RSDS DC Conditions

Parameter	Description	Typical	Units
Z_{OUT}	Output impedance	20	Ohms
R_S	Driver series resistor	294	Ohms
R_P	Driver parallel resistor	121	Ohms
R_T	Receiver termination	100	Ohms
V_{OH}	Output high voltage	1.35	V
V_{OL}	Output low voltage	1.15	V
V_{OD}	Output differential voltage	0.20	V
V_{CM}	Output common mode voltage	1.25	V
Z_{BACK}	Back impedance	101.5	Ohms
I_{DC}	DC output current	3.66	mA

sysCLOCK PLL Timing

Over Recommended Operating Conditions

Parameter	Descriptions	Conditions	Min.	Max.	Units
f_{IN}	Input Clock Frequency (CLKI, CLKFB)		25	420	MHz
		Input Divider (M) = 1; Feedback Divider (N) <= 4[5, 6]	18	25	MHz
f_{OUT}	Output Clock Frequency (CLKOP, CLKOS)		25	420	MHz
f_{OUT2}	K-Divider Output Frequency (CLKOK)		0.195	210	MHz
f_{VCO}	PLL VCO Frequency		420	840	MHz
f_{PFD}	Phase Detector Input Frequency		25	—	MHz
		Input Divider (M) = 1; Feedback Divider (N) <= 4[5, 6]	18	25	MHz
AC Characteristics					
t_{DT}	Output Clock Duty Cycle	Default duty cycle selected[3]	45	55	%
t_{PH}[4]	Output Phase Accuracy		—	0.05	UI
t_{OPJIT}[1]	Output Clock Period Jitter	f_{OUT} >= 100 MHz	—	+/-120	ps
		f_{OUT} < 100 MHz	—	0.02	UIPP
t_{SK}	Input Clock to Output Clock Skew	Divider ratio = integer	—	+/-200	ps
t_{W}	Output Clock Pulse Width	At 90% or 10%[3]	1	—	ns
t_{LOCK}[2]	PLL Lock-in Time		—	150	µs
t_{PA}	Programmable Delay Unit		100	450	ps
t_{IPJIT}	Input Clock Period Jitter	$f_{OUT} \geq$ 100 MHz	—	+/-200	ps
		f_{OUT} < 100 MHz	—	0.02	UI
t_{FBKDLY}	External Feedback Delay		—	10	ns
t_{HI}	Input Clock High Time	90% to 90%	0.5	—	ns
t_{LO}	Input Clock Low Time	10% to 10%	0.5	—	ns
t_{RST}	RST Pulse Width		10	—	ns

1. Jitter sample is taken over 10,000 samples of the primary PLL output with a clean reference clock.
2. Output clock is valid after t_{LOCK} for PLL reset and dynamic delay adjustment.
3. Using LVDS output buffers.
4. CLKOS as compared to CLKOP output.
5. When using an input frequency less than 25 MHz the output frequency must be less than or equal to 4 times the input frequency.
6. The on-chip oscillator can be used to provide reference clock input to the PLL provided the output frequency restriction for clock inputs below 25 MHz are followed.

Rev. A 0.19

MachXO Family Data Sheet
Pinout Information

June 2013 **Data Sheet DS1002**

Signal Descriptions

Signal Name	I/O	Descriptions
General Purpose		
P[Edge] [Row/Column Number]_[A/B/C/D/E/F]	I/O	[Edge] indicates the edge of the device on which the pad is located. Valid edge designations are L (Left), B (Bottom), R (Right), T (Top). [Row/Column Number] indicates the PFU row or the column of the device on which the PIO Group exists. When Edge is T (Top) or (Bottom), only need to specify Row Number. When Edge is L (Left) or R (Right), only need to specify Column Number. [A/B/C/D/E/F] indicates the PIO within the group to which the pad is connected. Some of these user programmable pins are shared with special function pins. When not used as special function pins, these pins can be programmed as I/Os for user logic. During configuration of the user-programmable I/Os, the user has an option to tri-state the I/Os and enable an internal pull-up resistor. This option also applies to unused pins (or those not bonded to a package pin). The default during configuration is for user-programmable I/Os to be tri-stated with an internal pull-up resistor enabled. When the device is erased, I/Os will be tri-stated with an internal pull-up resistor enabled.
GSRN	I	Global RESET signal (active low). Dedicated pad, when not in use it can be used as an I/O pin.
TSALL	I	TSALL is a dedicated pad for the global output enable signal. When TSALL is high all the outputs are tristated. It is a dual function pin. When not in use, it can be used as an I/O pin.
NC	—	No connect.
GND	—	GND - Ground. Dedicated pins.
V_{CC}	—	VCC - The power supply pins for core logic. Dedicated pins.
V_{CCAUX}	—	VCCAUX - the Auxiliary power supply pin. This pin powers up a variety of internal circuits including all the differential and referenced input buffers. Dedicated pins.
V_{CCIOx}	—	V_{CCIO} - The power supply pins for I/O Bank x. Dedicated pins.
SLEEPN[1]	I	Sleep Mode pin - Active low sleep pin.þ When this pin is held high, the device operates normally.þ This pin has a weak internal pull-up, but when unused, an external pull-up to V_{CC} is recommended. When driven low, the device moves into Sleep mode after a specified time.
PLL and Clock Functions (Used as user programmable I/O pins when not used for PLL or clock pins)		
[LOC][0]_PLL[T, C]_IN	—	Reference clock (PLL) input Pads: [LOC] indicates location. Valid designations are ULM (Upper PLL) and LLM (Lower PLL). T = true and C = complement.
[LOC][0]_PLL[T, C]_FB	—	Optional feedback (PLL) input Pads: [LOC] indicates location. Valid designations are ULM (Upper PLL) and LLM (Lower PLL). T = true and C = complement.
PCLK [n]_[1:0]	—	Primary Clock Pads, n per side.
Test and Programming (Dedicated pins)		
TMS	I	Test Mode Select input pin, used to control the 1149.1 state machine.
TCK	I	Test Clock input pin, used to clock the 1149.1 state machine.
TDI	I	Test Data input pin, used to load data into the device using an 1149.1 state machine.
TDO	O	Output pin -Test Data output pin used to shift data out of the device using 1149.1.

1. Applies to MachXO “C” devices only. NC for “E” devices.

LCMXO1200 and LCMXO2280 Logic Signal Connections: 100 TQFP (Cont.)

Pin Number	LCMXO1200				LCMXO2280			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
42	PB9A	4		T	PB12A	4		T
43	PB9B	4		C	PB12B	4		C
44	VCCIO4	4			VCCIO4	4		
45	PB10A	4		T	PB13A	4		T
46	PB10B	4		C	PB13B	4		C
47***	SLEEPN	-	SLEEPN		SLEEPN	-	SLEEPN	
48	PB11A	4		T	PB16A	4		T
49	PB11B	4		C	PB16B	4		C
50**	GNDIO3 GNDIO4	-			GNDIO3 GNDIO4	-		
51	PR16B	3			PR19B	3		
52	PR15B	3		C*	PR18B	3		C*
53	PR15A	3		T*	PR18A	3		T*
54	PR14B	3		C*	PR17B	3		C*
55	PR14A	3		T*	PR17A	3		T*
56	VCCIO3	3			VCCIO3	3		
57	PR12B	3		C*	PR15B	3		C*
58	PR12A	3		T*	PR15A	3		T*
59	GND	-			GND	-		
60	PR10B	3		C*	PR13B	3		C*
61	PR10A	3		T*	PR13A	3		T*
62	PR9B	3		C*	PR11B	3		C*
63	PR9A	3		T*	PR11A	3		T*
64	PR8B	2		C*	PR10B	2		C*
65	PR8A	2		T*	PR10A	2		T*
66	VCC	-			VCC	-		
67	PR6C	2			PR8C	2		
68	PR6B	2		C*	PR8B	2		C*
69	PR6A	2		T*	PR8A	2		T*
70	VCCIO2	2			VCCIO2	2		
71	PR4D	2			PR5D	2		
72	PR4B	2		C*	PR5B	2		C*
73	PR4A	2		T*	PR5A	2		T*
74	PR2B	2		C	PR3B	2		C*
75	PR2A	2		T	PR3A	2		T*
76**	GNDIO1 GNDIO2	-			GNDIO1 GNDIO2	-		
77	PT11C	1			PT15C	1		
78	PT11B	1		C	PT14B	1		C
79	PT11A	1		T	PT14A	1		T
80	VCCIO1	1			VCCIO1	1		
81	PT9E	1			PT12D	1		C

LCMXO256 and LCMXO640 Logic Signal Connections: 100 csBGA (Cont.)

LCMXO256					LCMXO640				
Ball Number	Ball Function	Bank	Dual Function	Differen-tial	Ball Number	Ball Function	Bank	Dual Function	Differen-tial
A4	GNDIO0	0			A4	GNDIO0	0		
B4	PT3A	0		T	B4	PT3B	0		C
A3	PT2F	0		C	A3	PT3A	0		T
B3	PT2E	0		T	B3	PT2F	0		C
A2	PT2D	0		C	A2	PT2E	0		T
C3	PT2C	0		T	C3	PT2B	0		C
A1	PT2B	0		C	A1	PT2C	0		
B2	PT2A	0		T	B2	PT2A	0		T
N9	GND	-			N9	GND	-		
B9	GND	-			B9	GND	-		
B5	VCCIO0	0			B5	VCCIO0	0		
A14	VCCIO0	0			A14	VCCIO1	1		
H14	VCCIO0	0			H14	VCCIO1	1		
P10	VCCIO1	1			P10	VCCIO2	2		
G1	VCCIO1	1			G1	VCCIO3	3		
P1	VCCIO1	1			P1	VCCIO3	3		

*NC for “E” devices.

**Primary clock inputs are single-ended.

LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections: 132 csBGA (Cont.)

LCMXO640					LCMXO1200					LCMXO2280				
Ball #	Ball Function	Bank	Dual Function	Differential	Ball #	Ball Function	Bank	Dual Function	Differential	Ball #	Ball Function	Bank	Dual Function	Differential
M9	PB7B	2		C	M9	PB9B	4		C	M9	PB12B	4		C
N10	PB7E	2		T	N10	PB9C	4		T	N10	PB12C	4		T
P10	PB7F	2		C	P10	PB9D	4		C	P10	PB12D	4		C
N11	GNDIO2	2			N11	GNDIO4	4			N11	GNDIO4	4		
P11	PB8C	2		T	P11	PB10A	4		T	P11	PB13C	4		T
M11	PB8D	2		C	M11	PB10B	4		C	M11	PB13D	4		C
P12	PB9C	2		T	P12	PB10C	4			P12	PB15B	4		
P13	PB9D	2		C	P13	PB11C	4		T	P13	PB16C	4		T
N12**	SLEEPN	-	SLEEPN		N12**	SLEEPN	-	SLEEPN		N12**	SLEEPN	-	SLEEPN	
P14	PB9F	2			P14	PB11D	4		C	P14	PB16D	4		C
N14	PR11D	1		C	N14	PR16B	3		C	N14	PR19B	3		C
M14	PR11C	1		T	M14	PR15B	3		C*	M14	PR18B	3		C*
N13	PR11B	1		C	N13	PR16A	3		T	N13	PR19A	3		T
M12	PR11A	1		T	M12	PR15A	3		T*	M12	PR18A	3		T*
M13	PR10B	1		C	M13	PR14B	3		C*	M13	PR17B	3		C*
L14	PR10A	1		T	L14	PR14A	3		T*	L14	PR17A	3		T*
L13	GNDIO1	1			L13	GNDIO3	3			L13	GNDIO3	3		
K14	PR8D	1		C	K14	PR12B	3		C*	K14	PR15B	3		C*
K13	PR8C	1		T	K13	PR12A	3		T*	K13	PR15A	3		T*
K12	PR8B	1		C	K12	PR11B	3		C*	K12	PR14B	3		C*
J13	PR8A	1		T	J13	PR11A	3		T*	J13	PR14A	3		T*
J12	PR7C	1			J12	PR10B	3		C*	J12	PR13B	3		C*
H14	PR7B	1		C	H14	PR10A	3		T*	H14	PR13A	3		T*
H13	PR7A	1		T	H13	PR9B	3		C*	H13	PR11B	3		C*
H12	PR6D	1		C	H12	PR9A	3		T*	H12	PR11A	3		T*
G13	PR6C	1		T	G13	PR8B	2		C*	G13	PR10B	2		C*
G14	PR6B	1			G14	PR8A	2		T*	G14	PR10A	2		T*
G12	VCC	-			G12	VCC	-			G12	VCC	-		
F14	PR5D	1		C	F14	PR6C	2			F14	PR8C	2		
F13	PR5C	1		T	F13	PR6B	2		C*	F13	PR8B	2		C*
F12	PR4D	1		C	F12	PR6A	2		T*	F12	PR8A	2		T*
E13	PR4C	1		T	E13	PR5B	2		C*	E13	PR7B	2		C*
E14	PR4B	1			E14	PR5A	2		T*	E14	PR7A	2		T*
D13	GNDIO1	1			D13	GNDIO2	2			D13	GNDIO2	2		
D14	PR3D	1		C	D14	PR4B	2		C*	D14	PR5B	2		C*
D12	PR3C	1		T	D12	PR4A	2		T*	D12	PR5A	2		T*
C14	PR2D	1		C	C14	PR3D	2		C	C14	PR4D	2		C
B14	PR2C	1		T	B14	PR2B	2		C	B14	PR3B	2		C*
C13	PR2B	1		C	C13	PR3C	2		T	C13	PR4C	2		T
A14	PR2A	1		T	A14	PR2A	2		T	A14	PR3A	2		T*
A13	PT9F	0		C	A13	PT11D	1		C	A13	PT16D	1		C
A12	PT9E	0		T	A12	PT11B	1		C	A12	PT16B	1		C
B13	PT9D	0		C	B13	PT11C	1		T	B13	PT16C	1		T
B12	PT9C	0		T	B12	PT10F	1			B12	PT15D	1		
C12	PT9B	0		C	C12	PT11A	1		T	C12	PT16A	1		T
A11	PT9A	0		T	A11	PT10D	1		C	A11	PT14B	1		C
C11	PT8C	0			C11	PT10C	1		T	C11	PT14A	1		T
A10	GNDIO0	0			A10	GNDIO1	1			A10	GNDIO1	1		
B10	PT7F	0		C	B10	PT9F	1		C	B10	PT12F	1		C
C10	PT7E	0		T	C10	PT9E	1		T	C10	PT12E	1		T

LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections: 256 caBGA / 256 ftBGA (Cont.)

LCMXO640					LCMXO1200					LCMXO2280				
Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential
E11	NC				E11	PT10D	1		C	E11	PT15B	1		C
E10	NC				E10	PT10C	1		T	E10	PT15A	1		T
D12	PT9D	0		C	D12	PT10B	1		C	D12	PT14D	1		C
D11	PT9C	0		T	D11	PT10A	1		T	D11	PT14C	1		T
A14	PT7F	0		C	A14	PT9F	1		C	A14	PT14B	1		C
A13	PT7E	0		T	A13	PT9E	1		T	A13	PT14A	1		T
C12	PT8B	0		C	C12	PT9D	1		C	C12	PT13D	1		C
C11	PT8A	0		T	C11	PT9C	1		T	C11	PT13C	1		T
-	-				VCCIO1	VCCIO1	1			VCCIO1	VCCIO1	1		
-	-				GND	GNDIO1	1			GND	GNDIO1	1		
B12	PT7B	0		C	B12	PT9B	1		C	B12	PT12D	1		C
B11	PT7A	0		T	B11	PT9A	1		T	B11	PT12C	1		T
A12	PT7D	0		C	A12	PT8F	1		C	A12	PT12B	1		C
A11	PT7C	0		T	A11	PT8E	1		T	A11	PT12A	1		T
GND	GND	-			GND	GND	-			GND	GND	-		
B10	PT5D	0		C	B10	PT8D	1		C	B10	PT11B	1		C
B9	PT5C	0		T	B9	PT8C	1		T	B9	PT11A	1		T
D10	PT8D	0		C	D10	PT8B	1		C	D10	PT10F	1		C
D9	PT8C	0		T	D9	PT8A	1		T	D9	PT10E	1		T
-	-				VCCIO1	VCCIO1	1			VCCIO1	VCCIO1	1		
-	-				GND	GNDIO1	1			GND	GNDIO1	1		
C10	PT6D	0		C	C10	PT7F	1		C	C10	PT10D	1		C
C9	PT6C	0		T	C9	PT7E	1		T	C9	PT10C	1		T
A9	PT6B	0	PCLK0_1***	C	A9	PT7D	1	PCLK1_1***	C	A9	PT10B	1	PCLK1_1***	C
A10	PT6A	0		T	A10	PT7C	1		T	A10	PT10A	1		T
E9	PT9B	0		C	E9	PT7B	1		C	E9	PT9D	1		C
E8	PT9A	0		T	E8	PT7A	1		T	E8	PT9C	1		T
D7	PT5B	0	PCLK0_0***	C	D7	PT6F	0	PCLK1_0***	C	D7	PT9B	1	PCLK1_0***	C
D8	PT5A	0		T	D8	PT6E	0		T	D8	PT9A	1		T
VCCIO0	VCCIO0	0			VCCIO0	VCCIO0	0			VCCIO0	VCCIO0	0		
GND	GNDIO0	0			GND	GNDIO0	0			GND	GNDIO0	0		
C8	PT4F	0		C	C8	PT6D	0		C	C8	PT8D	0		C
B8	PT4E	0		T	B8	PT6C	0		T	B8	PT8C	0		T
A8	VCCAUX	-			A8	VCCAUX	-			A8	VCCAUX	-		
A7	PT4D	0		C	A7	PT6B	0		C	A7	PT7D	0		C
A6	PT4C	0		T	A6	PT6A	0		T	A6	PT7C	0		T
VCC	VCC	-			VCC	VCC	-			VCC	VCC	-		
B7	PT4B	0		C	B7	PT5F	0		C	B7	PT7B	0		C
B6	PT4A	0		T	B6	PT5E	0		T	B6	PT7A	0		T
C6	PT3C	0		T	C6	PT5C	0		T	C6	PT6A	0		T
C7	PT3D	0		C	C7	PT5D	0		C	C7	PT6B	0		C
A5	PT3E	0		T	A5	PT5A	0		T	A5	PT6C	0		T
A4	PT3F	0		C	A4	PT5B	0		C	A4	PT6D	0		C
E7	NC				E7	PT4C	0		T	E7	PT6E	0		T
E6	NC				E6	PT4D	0		C	E6	PT6F	0		C
B5	PT3B	0		C	B5	PT3F	0		C	B5	PT5D	0		C
B4	PT3A	0		T	B4	PT3E	0		T	B4	PT5C	0		T
D5	PT2D	0		C	D5	PT3D	0		C	D5	PT5B	0		C
D6	PT2C	0		T	D6	PT3C	0		T	D6	PT5A	0		T
C4	PT2E	0		T	C4	PT4A	0		T	C4	PT4A	0		T
C5	PT2F	0		C	C5	PT4B	0		C	C5	PT4B	0		C
-	-	-			-	-	-			GND	GND	-		
D4	NC				D4	PT2D	0		C	D4	PT3D	0		C

LCMXO2280 Logic Signal Connections: 324 ftBGA (Cont.)

LCMXO2280				
Ball Number	**Ball Function**	**Bank**	**Dual Function**	**Differential**
J13	PR10C	2		T
M18	PR10B	2		C*
L18	PR10A	2		T*
GND	GNDIO2	2		
VCCIO2	VCCIO2	2		
H16	PR9D	2		C
H14	PR9C	2		T
K18	PR9B	2		C*
J18	PR9A	2		T*
J17	PR8D	2		C
VCC	VCC	-		
H18	PR8C	2		T
H17	PR8B	2		C*
G17	PR8A	2		T*
H13	PR7D	2		C
H15	PR7C	2		T
G18	PR7B	2		C*
F18	PR7A	2		T*
G14	PR6D	2		C
G16	PR6C	2		T
VCCIO2	VCCIO2	2		
GND	GNDIO2	2		
E18	PR6B	2		C*
F17	PR6A	2		T*
G13	PR5D	2		C
G15	PR5C	2		T
E17	PR5B	2		C*
E16	PR5A	2		T*
GND	GND	-		
F15	PR4D	2		C
E15	PR4C	2		T
D17	PR4B	2		C*
D18	PR4A	2		T*
B18	PR3D	2		C
C18	PR3C	2		T
C16	PR3B	2		C*
D16	PR3A	2		T*
C17	PR2B	2		C
D15	PR2A	2		T
VCCIO2	VCCIO2	2		
GND	GNDIO2	2		
GND	GNDIO1	1		
VCCIO1	VCCIO1	1		

Thermal Management

Thermal management is recommended as part of any sound FPGA design methodology. To assess the thermal characteristics of a system, Lattice specifies a maximum allowable junction temperature in all device data sheets. Designers must complete a thermal analysis of their specific design to ensure that the device and package do not exceed the junction temperature limits. Refer to the Thermal Management document to find the device/package specific thermal values.

For Further Information

For further information regarding Thermal Management, refer to the following:

- Thermal Management document
- TN1090 - Power Estimation and Management for MachXO Devices
- Power Calculator tool included with the Lattice ispLEVER design tool, or as a standalone download from www.latticesemi.com/software

Conventional Packaging

Commercial

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO256C-3T100C	256	1.8V/2.5V/3.3V	78	-3	TQFP	100	COM
LCMXO256C-4T100C	256	1.8V/2.5V/3.3V	78	-4	TQFP	100	COM
LCMXO256C-5T100C	256	1.8V/2.5V/3.3V	78	-5	TQFP	100	COM
LCMXO256C-3M100C	256	1.8V/2.5V/3.3V	78	-3	csBGA	100	COM
LCMXO256C-4M100C	256	1.8V/2.5V/3.3V	78	-4	csBGA	100	COM
LCMXO256C-5M100C	256	1.8V/2.5V/3.3V	78	-5	csBGA	100	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO640C-3T100C	640	1.8V/2.5V/3.3V	74	-3	TQFP	100	COM
LCMXO640C-4T100C	640	1.8V/2.5V/3.3V	74	-4	TQFP	100	COM
LCMXO640C-5T100C	640	1.8V/2.5V/3.3V	74	-5	TQFP	100	COM
LCMXO640C-3M100C	640	1.8V/2.5V/3.3V	74	-3	csBGA	100	COM
LCMXO640C-4M100C	640	1.8V/2.5V/3.3V	74	-4	csBGA	100	COM
LCMXO640C-5M100C	640	1.8V/2.5V/3.3V	74	-5	csBGA	100	COM
LCMXO640C-3T144C	640	1.8V/2.5V/3.3V	113	-3	TQFP	144	COM
LCMXO640C-4T144C	640	1.8V/2.5V/3.3V	113	-4	TQFP	144	COM
LCMXO640C-5T144C	640	1.8V/2.5V/3.3V	113	-5	TQFP	144	COM
LCMXO640C-3M132C	640	1.8V/2.5V/3.3V	101	-3	csBGA	132	COM
LCMXO640C-4M132C	640	1.8V/2.5V/3.3V	101	-4	csBGA	132	COM
LCMXO640C-5M132C	640	1.8V/2.5V/3.3V	101	-5	csBGA	132	COM
LCMXO640C-3B256C	640	1.8V/2.5V/3.3V	159	-3	caBGA	256	COM
LCMXO640C-4B256C	640	1.8V/2.5V/3.3V	159	-4	caBGA	256	COM
LCMXO640C-5B256C	640	1.8V/2.5V/3.3V	159	-5	caBGA	256	COM
LCMXO640C-3FT256C	640	1.8V/2.5V/3.3V	159	-3	ftBGA	256	COM
LCMXO640C-4FT256C	640	1.8V/2.5V/3.3V	159	-4	ftBGA	256	COM
LCMXO640C-5FT256C	640	1.8V/2.5V/3.3V	159	-5	ftBGA	256	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO1200C-3T100C	1200	1.8V/2.5V/3.3V	73	-3	TQFP	100	COM
LCMXO1200C-4T100C	1200	1.8V/2.5V/3.3V	73	-4	TQFP	100	COM
LCMXO1200C-5T100C	1200	1.8V/2.5V/3.3V	73	-5	TQFP	100	COM
LCMXO1200C-3T144C	1200	1.8V/2.5V/3.3V	113	-3	TQFP	144	COM
LCMXO1200C-4T144C	1200	1.8V/2.5V/3.3V	113	-4	TQFP	144	COM
LCMXO1200C-5T144C	1200	1.8V/2.5V/3.3V	113	-5	TQFP	144	COM
LCMXO1200C-3M132C	1200	1.8V/2.5V/3.3V	101	-3	csBGA	132	COM
LCMXO1200C-4M132C	1200	1.8V/2.5V/3.3V	101	-4	csBGA	132	COM
LCMXO1200C-5M132C	1200	1.8V/2.5V/3.3V	101	-5	csBGA	132	COM
LCMXO1200C-3B256C	1200	1.8V/2.5V/3.3V	211	-3	caBGA	256	COM
LCMXO1200C-4B256C	1200	1.8V/2.5V/3.3V	211	-4	caBGA	256	COM
LCMXO1200C-5B256C	1200	1.8V/2.5V/3.3V	211	-5	caBGA	256	COM
LCMXO1200C-3FT256C	1200	1.8V/2.5V/3.3V	211	-3	ftBGA	256	COM
LCMXO1200C-4FT256C	1200	1.8V/2.5V/3.3V	211	-4	ftBGA	256	COM
LCMXO1200C-5FT256C	1200	1.8V/2.5V/3.3V	211	-5	ftBGA	256	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO2280C-3T100C	2280	1.8V/2.5V/3.3V	73	-3	TQFP	100	COM
LCMXO2280C-4T100C	2280	1.8V/2.5V/3.3V	73	-4	TQFP	100	COM
LCMXO2280C-5T100C	2280	1.8V/2.5V/3.3V	73	-5	TQFP	100	COM
LCMXO2280C-3T144C	2280	1.8V/2.5V/3.3V	113	-3	TQFP	144	COM
LCMXO2280C-4T144C	2280	1.8V/2.5V/3.3V	113	-4	TQFP	144	COM
LCMXO2280C-5T144C	2280	1.8V/2.5V/3.3V	113	-5	TQFP	144	COM
LCMXO2280C-3M132C	2280	1.8V/2.5V/3.3V	101	-3	csBGA	132	COM
LCMXO2280C-4M132C	2280	1.8V/2.5V/3.3V	101	-4	csBGA	132	COM
LCMXO2280C-5M132C	2280	1.8V/2.5V/3.3V	101	-5	csBGA	132	COM
LCMXO2280C-3B256C	2280	1.8V/2.5V/3.3V	211	-3	caBGA	256	COM
LCMXO2280C-4B256C	2280	1.8V/2.5V/3.3V	211	-4	caBGA	256	COM
LCMXO2280C-5B256C	2280	1.8V/2.5V/3.3V	211	-5	caBGA	256	COM
LCMXO2280C-3FT256C	2280	1.8V/2.5V/3.3V	211	-3	ftBGA	256	COM
LCMXO2280C-4FT256C	2280	1.8V/2.5V/3.3V	211	-4	ftBGA	256	COM
LCMXO2280C-5FT256C	2280	1.8V/2.5V/3.3V	211	-5	ftBGA	256	COM
LCMXO2280C-3FT324C	2280	1.8V/2.5V/3.3V	271	-3	ftBGA	324	COM
LCMXO2280C-4FT324C	2280	1.8V/2.5V/3.3V	271	-4	ftBGA	324	COM
LCMXO2280C-5FT324C	2280	1.8V/2.5V/3.3V	271	-5	ftBGA	324	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO256E-3T100C	256	1.2V	78	-3	TQFP	100	COM
LCMXO256E-4T100C	256	1.2V	78	-4	TQFP	100	COM
LCMXO256E-5T100C	256	1.2V	78	-5	TQFP	100	COM
LCMXO256E-3M100C	256	1.2V	78	-3	csBGA	100	COM
LCMXO256E-4M100C	256	1.2V	78	-4	csBGA	100	COM
LCMXO256E-5M100C	256	1.2V	78	-5	csBGA	100	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO640E-3T100C	640	1.2V	74	-3	TQFP	100	COM
LCMXO640E-4T100C	640	1.2V	74	-4	TQFP	100	COM
LCMXO640E-5T100C	640	1.2V	74	-5	TQFP	100	COM
LCMXO640E-3M100C	640	1.2V	74	-3	csBGA	100	COM
LCMXO640E-4M100C	640	1.2V	74	-4	csBGA	100	COM
LCMXO640E-5M100C	640	1.2V	74	-5	csBGA	100	COM
LCMXO640E-3T144C	640	1.2V	113	-3	TQFP	144	COM
LCMXO640E-4T144C	640	1.2V	113	-4	TQFP	144	COM
LCMXO640E-5T144C	640	1.2V	113	-5	TQFP	144	COM
LCMXO640E-3M132C	640	1.2V	101	-3	csBGA	132	COM
LCMXO640E-4M132C	640	1.2V	101	-4	csBGA	132	COM
LCMXO640E-5M132C	640	1.2V	101	-5	csBGA	132	COM
LCMXO640E-3B256C	640	1.2V	159	-3	caBGA	256	COM
LCMXO640E-4B256C	640	1.2V	159	-4	caBGA	256	COM
LCMXO640E-5B256C	640	1.2V	159	-5	caBGA	256	COM
LCMXO640E-3FT256C	640	1.2V	159	-3	ftBGA	256	COM
LCMXO640E-4FT256C	640	1.2V	159	-4	ftBGA	256	COM
LCMXO640E-5FT256C	640	1.2V	159	-5	ftBGA	256	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO1200E-3T100C	1200	1.2V	73	-3	TQFP	100	COM
LCMXO1200E-4T100C	1200	1.2V	73	-4	TQFP	100	COM
LCMXO1200E-5T100C	1200	1.2V	73	-5	TQFP	100	COM
LCMXO1200E-3T144C	1200	1.2V	113	-3	TQFP	144	COM
LCMXO1200E-4T144C	1200	1.2V	113	-4	TQFP	144	COM
LCMXO1200E-5T144C	1200	1.2V	113	-5	TQFP	144	COM
LCMXO1200E-3M132C	1200	1.2V	101	-3	csBGA	132	COM
LCMXO1200E-4M132C	1200	1.2V	101	-4	csBGA	132	COM
LCMXO1200E-5M132C	1200	1.2V	101	-5	csBGA	132	COM
LCMXO1200E-3B256C	1200	1.2V	211	-3	caBGA	256	COM
LCMXO1200E-4B256C	1200	1.2V	211	-4	caBGA	256	COM
LCMXO1200E-5B256C	1200	1.2V	211	-5	caBGA	256	COM
LCMXO1200E-3FT256C	1200	1.2V	211	-3	ftBGA	256	COM
LCMXO1200E-4FT256C	1200	1.2V	211	-4	ftBGA	256	COM
LCMXO1200E-5FT256C	1200	1.2V	211	-5	ftBGA	256	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO2280E-3T100C	2280	1.2V	73	-3	TQFP	100	COM
LCMXO2280E-4T100C	2280	1.2V	73	-4	TQFP	100	COM
LCMXO2280E-5T100C	2280	1.2V	73	-5	TQFP	100	COM
LCMXO2280E-3T144C	2280	1.2V	113	-3	TQFP	144	COM
LCMXO2280E-4T144C	2280	1.2V	113	-4	TQFP	144	COM
LCMXO2280E-5T144C	2280	1.2V	113	-5	TQFP	144	COM
LCMXO2280E-3M132C	2280	1.2V	101	-3	csBGA	132	COM
LCMXO2280E-4M132C	2280	1.2V	101	-4	csBGA	132	COM
LCMXO2280E-5M132C	2280	1.2V	101	-5	csBGA	132	COM
LCMXO2280E-3B256C	2280	1.2V	211	-3	caBGA	256	COM
LCMXO2280E-4B256C	2280	1.2V	211	-4	caBGA	256	COM
LCMXO2280E-5B256C	2280	1.2V	211	-5	caBGA	256	COM
LCMXO2280E-3FT256C	2280	1.2V	211	-3	ftBGA	256	COM
LCMXO2280E-4FT256C	2280	1.2V	211	-4	ftBGA	256	COM
LCMXO2280E-5FT256C	2280	1.2V	211	-5	ftBGA	256	COM
LCMXO2280E-3FT324C	2280	1.2V	271	-3	ftBGA	324	COM
LCMXO2280E-4FT324C	2280	1.2V	271	-4	ftBGA	324	COM
LCMXO2280E-5FT324C	2280	1.2V	271	-5	ftBGA	324	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO256E-3T100I	256	1.2V	78	-3	TQFP	100	IND
LCMXO256E-4T100I	256	1.2V	78	-4	TQFP	100	IND
LCMXO256E-3M100I	256	1.2V	78	-3	csBGA	100	IND
LCMXO256E-4M100I	256	1.2V	78	-4	csBGA	100	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO640E-3T100I	640	1.2V	74	-3	TQFP	100	IND
LCMXO640E-4T100I	640	1.2V	74	-4	TQFP	100	IND
LCMXO640E-3M100I	640	1.2V	74	-3	csBGA	100	IND
LCMXO640E-4M100I	640	1.2V	74	-4	csBGA	100	IND
LCMXO640E-3T144I	640	1.2V	113	-3	TQFP	144	IND
LCMXO640E-4T144I	640	1.2V	113	-4	TQFP	144	IND
LCMXO640E-3M132I	640	1.2V	101	-3	csBGA	132	IND
LCMXO640E-4M132I	640	1.2V	101	-4	csBGA	132	IND
LCMXO640E-3B256I	640	1.2V	159	-3	caBGA	256	IND
LCMXO640E-4B256I	640	1.2V	159	-4	caBGA	256	IND
LCMXO640E-3FT256I	640	1.2V	159	-3	ftBGA	256	IND
LCMXO640E-4FT256I	640	1.2V	159	-4	ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO1200E-3T100I	1200	1.2V	73	-3	TQFP	100	IND
LCMXO1200E-4T100I	1200	1.2V	73	-4	TQFP	100	IND
LCMXO1200E-3T144I	1200	1.2V	113	-3	TQFP	144	IND
LCMXO1200E-4T144I	1200	1.2V	113	-4	TQFP	144	IND
LCMXO1200E-3M132I	1200	1.2V	101	-3	csBGA	132	IND
LCMXO1200E-4M132I	1200	1.2V	101	-4	csBGA	132	IND
LCMXO1200E-3B256I	1200	1.2V	211	-3	caBGA	256	IND
LCMXO1200E-4B256I	1200	1.2V	211	-4	caBGA	256	IND
LCMXO1200E-3FT256I	1200	1.2V	211	-3	ftBGA	256	IND
LCMXO1200E-4FT256I	1200	1.2V	211	-4	ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO2280E-3T100I	2280	1.2V	73	-3	TQFP	100	IND
LCMXO2280E-4T100I	2280	1.2V	73	-4	TQFP	100	IND
LCMXO2280E-3T144I	2280	1.2V	113	-3	TQFP	144	IND
LCMXO2280E-4T144I	2280	1.2V	113	-4	TQFP	144	IND
LCMXO2280E-3M132I	2280	1.2V	101	-3	csBGA	132	IND
LCMXO2280E-4M132I	2280	1.2V	101	-4	csBGA	132	IND
LCMXO2280E-3B256I	2280	1.2V	211	-3	caBGA	256	IND
LCMXO2280E-4B256I	2280	1.2V	211	-4	caBGA	256	IND
LCMXO2280E-3FT256I	2280	1.2V	211	-3	ftBGA	256	IND
LCMXO2280E-4FT256I	2280	1.2V	211	-4	ftBGA	256	IND
LCMXO2280E-3FT324I	2280	1.2V	271	-3	ftBGA	324	IND
LCMXO2280E-4FT324I	2280	1.2V	271	-4	ftBGA	324	IND